

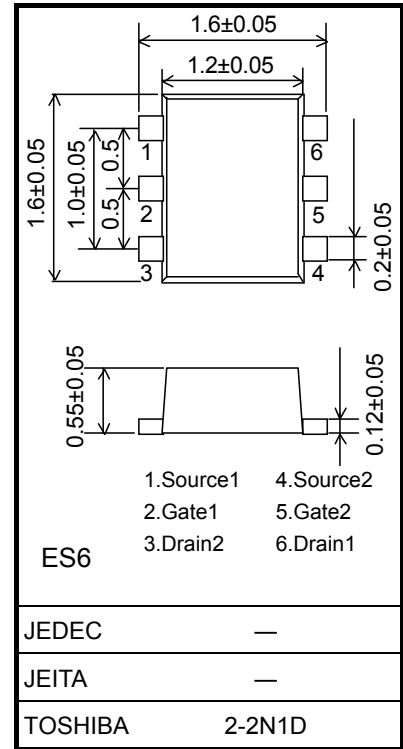
TOSHIBA Field-Effect Transistor Silicon N-Channel MOS Type

## SSM6N37FE

- High-Speed Switching Applications
- Analog Switching Applications

- 1.5-V drive
- Suitable for high-density mounting due to compact package
- Low ON-resistance
  - $R_{DS(ON)} = 5.60 \Omega$  (max) (@ $V_{GS} = 1.5 V$ )
  - $R_{DS(ON)} = 4.05 \Omega$  (max) (@ $V_{GS} = 1.8 V$ )
  - $R_{DS(ON)} = 3.02 \Omega$  (max) (@ $V_{GS} = 2.5 V$ )
  - $R_{DS(ON)} = 2.20 \Omega$  (max) (@ $V_{GS} = 4.5 V$ )

単位: mm



Weight: 3.0 mg (typ.)

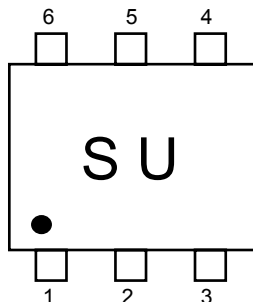
### Absolute Maximum Ratings (Ta = 25°C) (Q1, Q2 Common)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	20	V
Gate-source voltage	$V_{GSS}$	$\pm 10$	V
Drain current	DC	$I_D$	250
	Pulse	$I_{DP}$	500
Drain power dissipation	$P_D$ (Note 1)	150	mW
Channel temperature	$T_{ch}$	150	°C
Storage temperature	$T_{stg}$	-55 to 150	°C

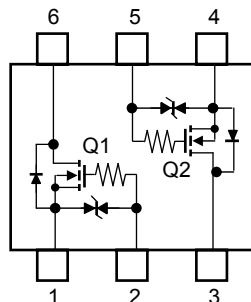
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating  
 Mounted on an FR4 board  
 (25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 0.135 mm<sup>2</sup> × 6)

### Marking



### Equivalent Circuit (top view)



Start of commercial production  
 2009-12

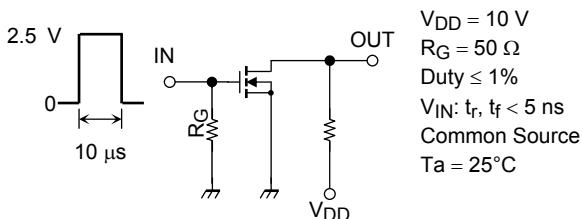
## Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	20	—	—	V
	$V_{(BR)DSX}$	$I_D = 1 \text{ mA}, V_{GS} = -10 \text{ V}$	12	—	—	
Drain cutoff current	$I_{DSS}$	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	1	$\mu\text{A}$
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	$\pm 1$	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = 3 \text{ V}, I_D = 1 \text{ mA}$	0.35	—	1.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3 \text{ V}, I_D = 100 \text{ mA}$ (Note 2)	0.14	0.28	—	S
Drain-source ON-resistance	$R_{DS(ON)}$	$I_D = 100 \text{ mA}, V_{GS} = 4.5 \text{ V}$ (Note 2)	—	1.65	2.20	$\Omega$
		$I_D = 50 \text{ mA}, V_{GS} = 2.5 \text{ V}$ (Note 2)	—	2.16	3.02	
		$I_D = 20 \text{ mA}, V_{GS} = 1.8 \text{ V}$ (Note 2)	—	2.66	4.05	
		$I_D = 10 \text{ mA}, V_{GS} = 1.5 \text{ V}$ (Note 2)	—	3.07	5.60	
Input capacitance	$C_{iss}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	12	—	$\text{pF}$
Output capacitance	$C_{oss}$		—	5.5	—	
Reverse transfer capacitance	$C_{rss}$		—	4.1	—	
Switching time	Turn-on time	$t_{on}$	$V_{DD} = 10 \text{ V}, I_D = 100 \text{ mA}$ $V_{GS} = 0 \text{ to } 2.5 \text{ V}, R_G = 50 \Omega$	—	18	ns
	Turn-off time	$t_{off}$		—	36	
Drain-source forward voltage	$V_{DSF}$	$I_D = -250 \text{ mA}, V_{GS} = 0 \text{ V}$ (Note 2)	—	-0.9	-1.2	V

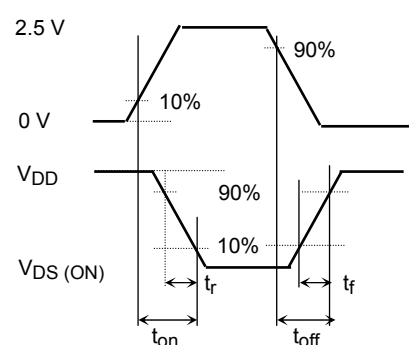
Note 2: Pulse test

## Switching Time Test Circuit (Q1, Q2 Common)

### (a) Test Circuit



### (b) $V_{IN}$



### (c) $V_{OUT}$

## Precaution

Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to be low (1mA for the SSM6N37FE). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

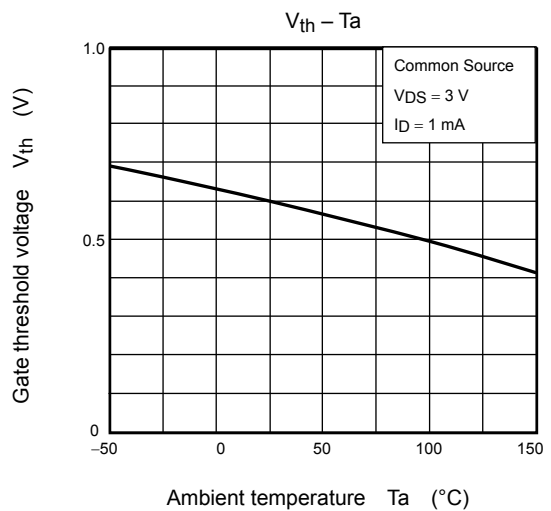
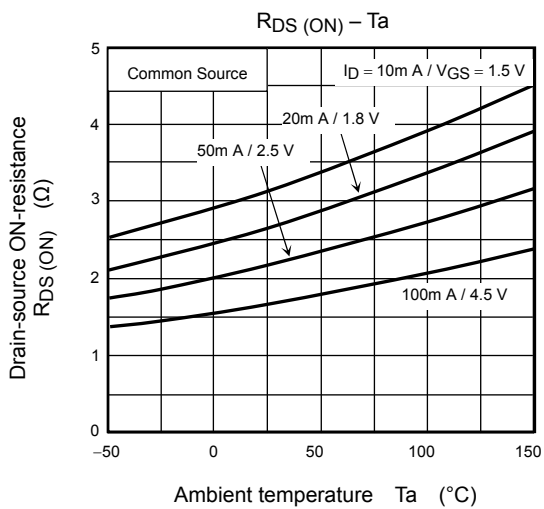
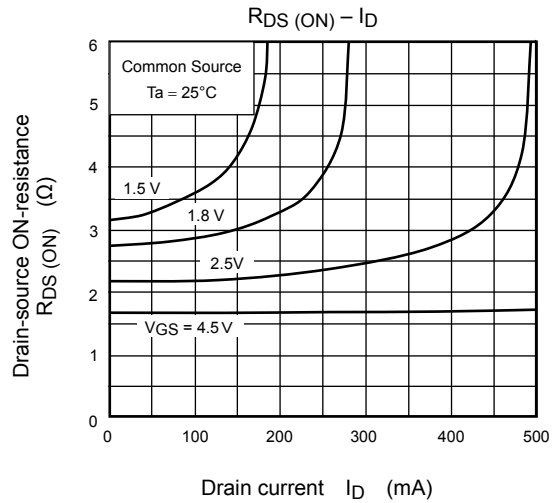
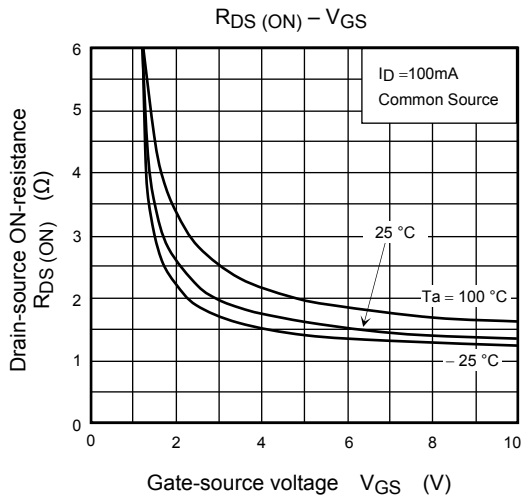
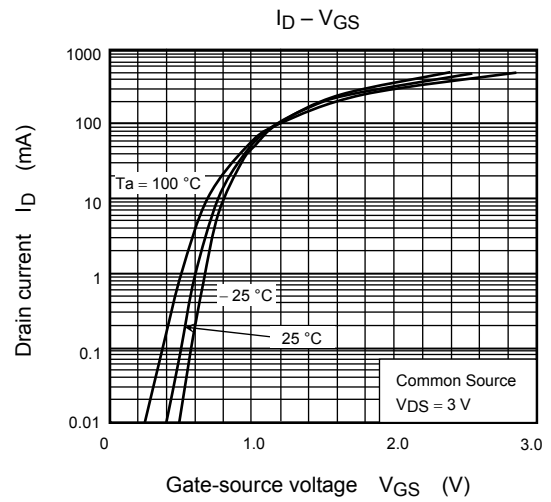
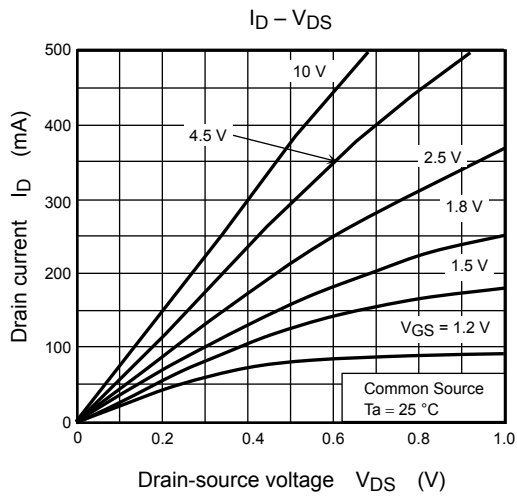
Do not use this device under avalanche mode. It may cause the device to break down.

## Handling Precaution

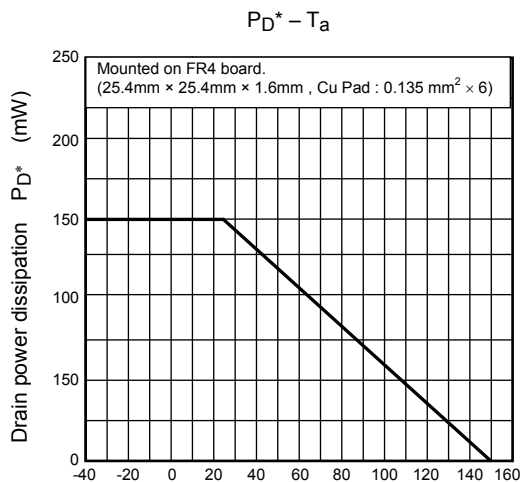
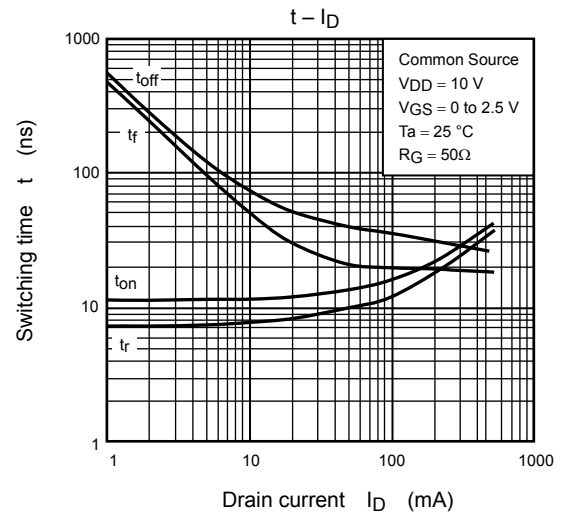
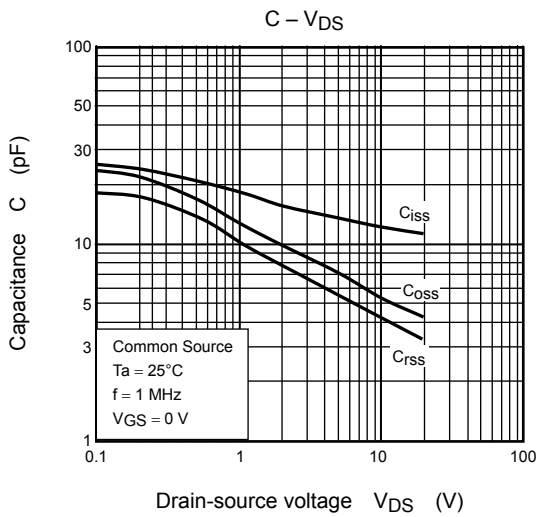
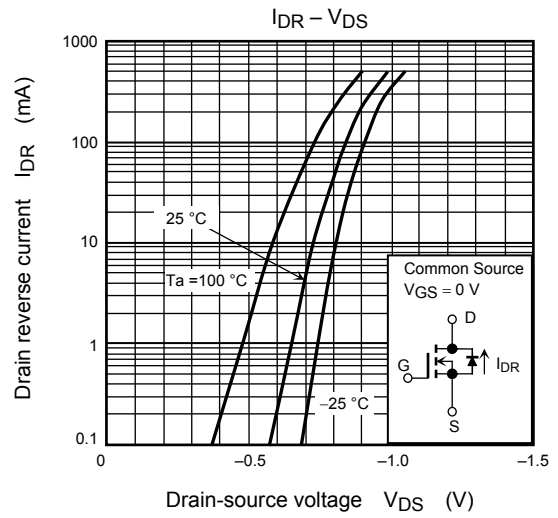
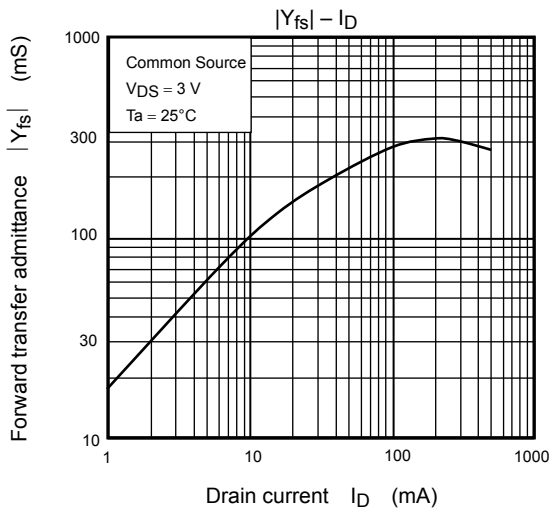
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

Thermal resistance  $R_{th(j-a)}$  and drain power dissipation  $P_D$  vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration.

(Q1, Q2 Common)



(Q1, Q2 Common)



\*:Total Rating Ambient temperature  $T_a$  ( $^\circ\text{C}$ )

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